



Docket No.: M4065.0127/P127-A  
(PATENT)

H/Response  
7/13/01  
A. Weller

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:  
Kie Y. Ahn, et al.

Application No.: 09/660,324

Group Art Unit: 2823

Filed: September 12, 2000

Examiner: E. Toledo

For: SILICON MULTI-CHIP MODULE  
PACKAGING WITH INTEGRATED  
PASSIVE COMPONENTS AND METHOD  
OF MAKING

RESPONSE

Commissioner for Patents  
Washington, DC 20231

Dear Sir:

In response to the Office Action dated April 11, 2001, applicants respectfully submit the following:

REMARKS

Claims 88-123 are presently pending in this application.

Claims 107-122 stand rejected under 35 U.S.C. § 112, second paragraph, as being indefinite for failing to particularly point out and distinctly claim the subject matter which applicant regards as the invention. Reconsideration is respectfully requested.

The Office Action states, “[c]laims 107-122 provides a method for use in a various circuit devices (i.e. RF communication systems), but, since the claim does not set forth any steps involved in the method/process, it is unclear what method/process

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